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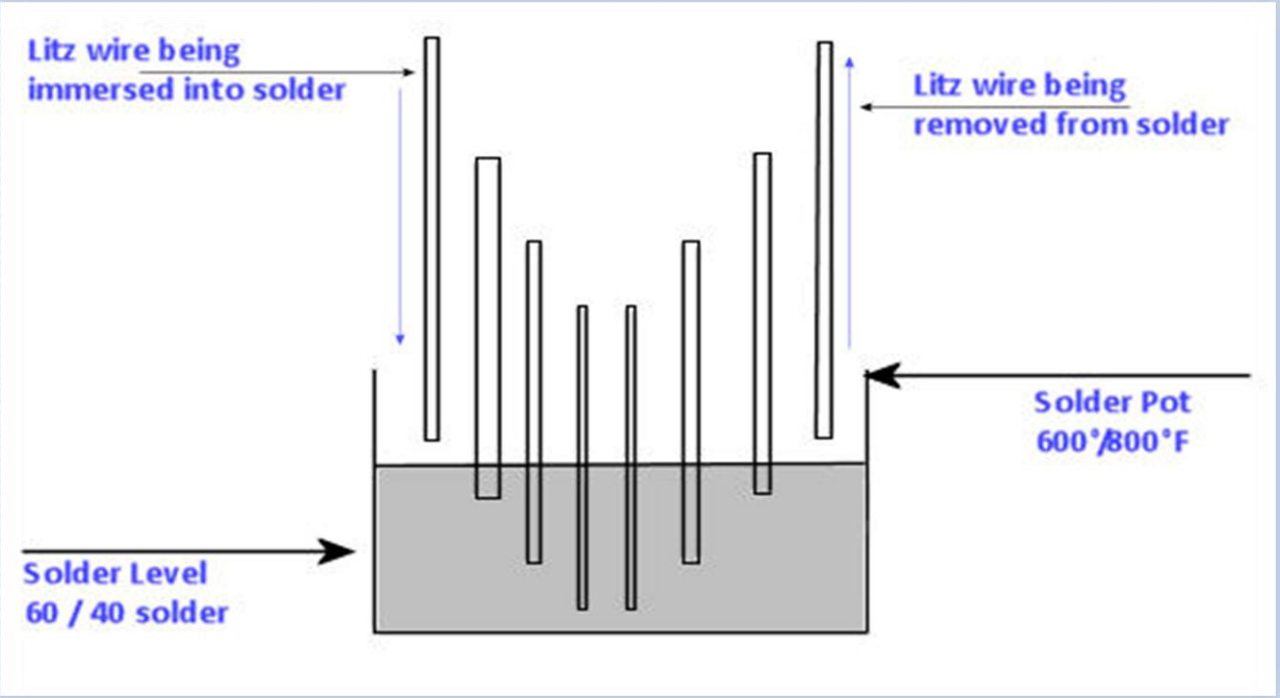
Soldering of Litz Wire



Soldering Time and Temperature			
Litz AWG Size	Nominal Dia. Litz Wire IN.	Average Immersion Time	Temperature of Solder F° & C°
2 – 9	0.3800 – 0.1680	12 sec	800° F – 426.67° C
10 – 19	0.1300 – 0.0500	10 sec	800° F – 426.67° C
20 – 23	0.0405 – 0.0305	8 sec	680° F – 360° C
24 – 29	0.0280 – 0.0185	6 sec	680° F – 360° C
30 – 36	0.0170 – 0.0100	5 sec	680° F – 360° C
37 - 42	0.0095 – 0.0040	4 sec	680° F – 360° C

The soldering stroke (immersion dip) should be a smooth, deliberate, continuous and unhurried movement. The downward movement of the Litz wire enters the solder and should be slow and encompass a horizontal movement that is parallel to or in the plane of the solder bath.

As the Litz wire is immersed into the solder, the film coating is removed, and oxides (contamination) are left on the surface of the solder pot due to the high surface tension effect of molten solder. The horizontal movement as discussed above allows the oxide contamination to be left behind the wire.

Last, and most important, is to skim the molten solder surface at adequate intervals with the piece of sheet metal or cardboard to prevent oxides from the film and any surface oxidation from adherence to the soldered Litz.